

AMENDMENTS TO THE CLAIMS:

This listing of the claims will replace all prior versions, and listings, of the claims in this application:

Please cancel claims 61, 66-87, and 89-93 without prejudice or disclaimer.

Listing of Claims:

1.-18. (Canceled).

19. (Currently Amended) A diffusion barrier comprising a plurality of stacked amorphous sub-layers, each sub-layer having a thickness of about 0.4 to about 4.5 nanometers (nm), wherein the plurality of stacked amorphous sub-layers are arranged collectively to inhibit diffusion of a chemical species through the diffusion barrier, and where the plurality of stacked amorphous sub-layers are between three and ten in number ~~or more stacked amorphous sub-layers~~, wherein the stacked amorphous sub-layers are of alternating composition, where an amorphous sub-layer of tantalum (Ta) alternates with an amorphous sub-layer of copper (Cu), wherein the amorphous sub-layers in the diffusion barrier are mutually adhesive, wherein the diffusion barrier is a circuit interconnect.

20.-60. (Canceled).

61. (Previously Presented) A diffusion barrier as in claim 19, where the plurality of sub-layers in the diffusion barrier are between three and ten in number.

62.-87. (Canceled).

88. (Previously Presented) A diffusion barrier as in claim 19, wherein the diffusion barrier is electrically conductive.

89.-93. (Canceled).